

Electronic Patent Application Fee Transmittal

Application Number:	10597514
Filing Date:	27-Jul-2006
Title of Invention:	Mold, Method of Forming the Same, and Method of Producing Polycrystalline Silicon Substrate Using the Mold
First Named Inventor/Applicant Name:	Youhei Sakai
Filer:	Lawrence James McClure/Diane Zynn
Attorney Docket Number:	81872.0124

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810